Features



High-Current VCOM Drive Op Amps for TFT LCDs

General Description

The MAX9650/MAX9651 are single- and dual-channel VCOM amplifiers with rail-to-rail inputs and outputs. The MAX9650/MAX9651 can drive up to 1300mA of peak current per channel and operate up to 20V.

The MAX9650/MAX9651 are designed to source and sink a high current quickly to hold the VCOM voltage stable in large TFT-LCD panels.

The MAX9650/MAX9651 feature 40V/µs slew rate and 35MHz bandwidth to guickly settle outputs for 120Hz frame rate and full HD television.

The MAX9650/MAX9651 feature output short-circuit protection and thermal shutdown. These devices are available in exposed pad packages for excellent heat dissipation.

Applications

TFT-LCD Panels Instrument Control Voltage Sources

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♦ 1300mA Peak Output Current

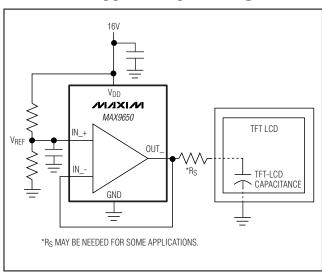
- ♦ Rail-to-Rail Inputs and Outputs
- ♦ Operates Up to 20V
- ♦ 40V/µs Slew Rate
- ♦ 35MHz Bandwidth
- **♦** 5mA Quiescent Current per Channel
- **♦** Excellent Heat Dissipation (Exposed Pad)

Ordering Information

| PART | AMPS PER PACKAGE | PIN- PACKAGE | TOP MARK |
|-------------|---------------------|-----------------|----------|
| MAX9650AZK+ | 1 | 5 SOT23 | ADSI |
| MAX9650AUA+ | 1 | 8 μMAX-EP* | AABI |
| MAX9650ATA+ | 1 | 8 TDFN-EP* | BKX |
| MAX9651AUA+ | 2 | 8 μMAX-EP* | AABH |
| MAX9651ATA+ | 2 | 8 TDFN-EP* | BKY |

Note: All devices are specified over the -40°C to +125°C operating range.

Typical Operating Circuit



⁺Denotes a lead-free/RoHS-compliant package.

^{*}EP = Exposed pad.

ABSOLUTE MAXIMUM RATINGS

| Supply Voltage (V_{DD} to GND)0.3V to +22V Any Other Pin to GND0.3V to (V_{DD} + 0.3V) |
|--|
| IN_+/IN (current)±20mA |
| OUT_ (current)1.3A |
| Continuous Power Dissipation (T _A = +70°C) |
| 5-Pin SOT23 (derate 3.7mW/°C above +70°C)297.4mW |
| 8-Pin µMAX-EP (derate 12.9mW/°C |
| above +70°C) |
| 8-Pin TDFN-EP (derate 23.8mW/°C |
| above +70°C)1951.2mW |

| Operating Temperature Range | 40°C to +125°C |
|-----------------------------------|----------------|
| Junction Temperature | +150°C |
| Storage Temperature Range | 65°C to +150°C |
| Lead Temperature (soldering, 10s) | +300°C |
| | |

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(VDD = 19V, VGND = 0, VCM = VOUT = VDD/2, TA = TMIN to TMAX, unless otherwise noted. Typical values are at TA = +25°C.) (Note 1)

| | PARAMETER | SYMBOL | CONDITION | IS | MIN | TYP | MAX | UNITS |
|----------------|------------------------------------|-----------------|--|---|---------------|---------------------------|--------------------------|---------|
| | Supply Voltage Range | V_{DD} | Guaranteed by PSRR | | 6 | | 20 | V |
| | Quiescent Current | I _{DD} | Per channel | | | 3.7 | 8 | mA |
| | High Output Voltage | V _{OH} | I _H = +5mA, V _{IN} = V _{DD} | | VDD - 0.30 | V _{DD} - 0.05 | | V |
| | Low Output Voltage | Vol | $I_L = -5mA$, $V_{IN} = 0$ | | | 0.05 | 0.30 | V |
| | Input Offact Voltage | \/aa | $T_A = +25^{\circ}C$ | | -14 | 3.5 | +14 | V |
| | Input Offset Voltage | Vos | $T_A = -40^{\circ}C \text{ to } +125^{\circ}C$ | | -17 | | +17 | \ \ |
| | Load Degulation | LR | $I_{OUT} = 0$ to -80 mA | | | +0.2 | | m\//m \ |
| | Load Regulation | Ln | $I_{OUT} = 0 \text{ to } + 80\text{mA}$ | | | -0.2 | | mV/mA |
| | Input Bias Current | I _{FB} | At V _{IN} = 9.5V | | | 0.01 | 1 | μΑ |
| www.Da | Voltage Gain | Ay | $A_V = 1V/V$, $R_L = 10k\Omega$, $C_L =$ | $A_V = 1V/V$, $R_L = 10k\Omega$, $C_L = 50pF$ | | | 1.01 | V/V |
| VV VV VV . D 6 | Power-Supply Rejection Ratio | PSRR | $V_{DD} = 6V \text{ to } 20V, V_{CM} = V_{C}$ | out = 3V | 70 | 95 | | dB |
| | Common-Mode Input Voltage Range | CMVR | Inferred from CMRR test | | 0.5 | | V _{DD} - 0.5 | V |
| | Common-Mode Rejection Ratio | CMRR | $0.5V \le V_{CM} \le V_{DD} - 0.5V$ | | 60 | 80 | | dB |
| | | | V _{OUT} = 9.5V | MAX9650AZK+ | 20 | | | |
| | Continuous Output Current | IO | (Note 2) | MAX9650AUA+ | 80 | | | mA |
| | | | V _{DD} = 15V, V _{OUT} = 7.5V | MAX9650ATA+ | | ±350 | | |
| | Transient Peak Output Current | I _{PK} | (Note 3) | | | ±1.3 | | А |
| | Bandwidth | BW | -3dB | | | 35 | | MHz |
| | Slew Rate | SR | 4V step, $C_L = 50pF$, $R_L = 10k\Omega$, $A_V = +1V/V$ | | | 40 | | V/µs |
| | Settling Time | ts | Settling to 0.1% of V_{OUT} , $I_L = 0$ to 1000mA, $R_S = 2.2\Omega$, $C_S = 0.1\mu F$ (Figure 1) | | | 2.0 | | μs |



ELECTRICAL CHARACTERISTICS (continued)

(V_{DD} = 19V, V_{GND} = 0, V_{CM} = V_{OUT} = V_{DD}/2, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
|-------------------------------|-------------------|------------|-----|------|-----|-------|
| Maximum Load Capacitance | CLOAD | (Note 4) | | 150 | | nF |
| Noninverting Input Resistance | R _{IN+} | (Note 5) | | 100 | | МΩ |
| Inverting Input Resistance | R _{IN} - | (Note 5) | | 100 | | MΩ |
| Input Capacitance | CIN | | | 3 | | рF |
| Thermal Shutdown | | | | +170 | | °C |
| Thermal Shutdown Hysteresis | | | | 15 | | °C |

Note 1: All devices are 100% production tested at T_A = +25°C. All temperature limits are guaranteed by design.

Note 2: Continuous output current is tested with one output at a time.

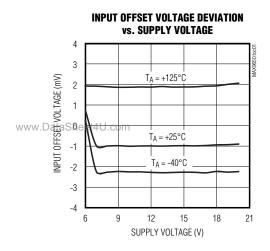
Note 3: See the Thermal Shutdown with Temperature Hysteresis section.

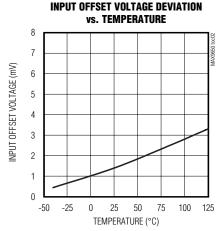
Note 4: A series resistor can extend load capacitance range. The settling time can be optimized by a small series resistance. See the *Applications Information* section for more information.

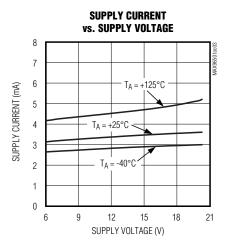
Note 5: Inputs are protected by back-to-back diodes.

_Typical Operating Characteristics

 $(V_{DD} = 19V, GND = 0, V_{CM} = V_{OUT} = V_{DD}/2, T_A = +25^{\circ}C, unless otherwise specified.)$

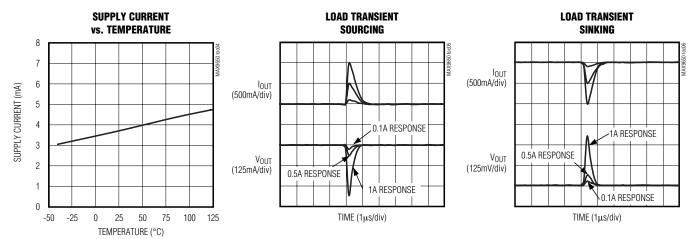


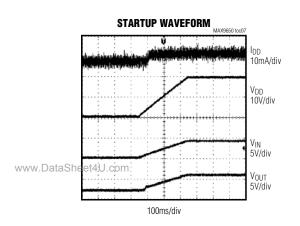


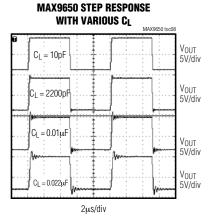


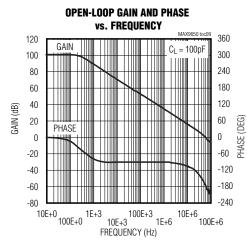
Typical Operating Characteristics (continued)

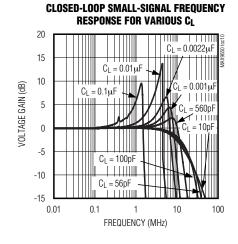
 $(V_{DD} = 19V, GND = 0, V_{CM} = V_{OUT} = V_{DD}/2, T_A = +25$ °C, unless otherwise specified.)

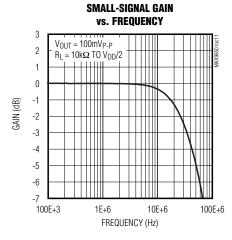


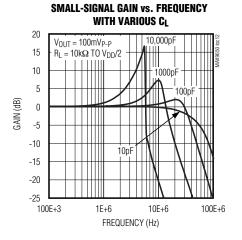












4 ______*N*IXI/N

Pin Description

| | PIN | | | | |
|-------|---------|---------|-----------------|--|--|
| MAX | MAX9650 | | NAME | FUNCTION | |
| SOT23 | μМΑХ | MAX9651 | | | |
| 1 | 6 | 1 | OUTA | VCOM Output A | |
| 2 | 4 | 4 | GND | Ground | |
| 3 | 3 | 3 | INA+ | Positive Input A | |
| 4 | 2 | 2 | INA- | Negative Input A | |
| 5 | 7 | 8 | V _{DD} | Positive-Supply Input. Bypass V _{DD} to GND with a 0.1µF capacitor as close a possible to the device. | |
| _ | _ | 5 | INB+ | Positive Input B | |
| _ | _ | 6 | INB- | Negative Input B | |
| _ | _ | 7 | OUTB | VCOM Output B | |
| _ | 1, 5, 8 | _ | N.C. | No Connection. Not internally connected. | |
| _ | _ | _ | EP | Exposed Pad. EP is internally connected to GND. Connect EP to GND. | |

Detailed Description

The MAX9650/MAX9651 operational rail-to-rail input/output amplifiers hold the VCOM voltage stable while providing the ability to source and sink a high current quickly (1.3A) into a capacitive load such as the backplane of a TFT-LCD panel.

Thermal Shutdown with Temperature Hysteresis

www.DTherMAX9650/MAX9651 are capable of high output currents and feature thermal-shutdown protection with temperature hysteresis. When the die temperature reaches +170°C, the device shuts down. When the die cools down by 15°C, the device turns on again. In a TFT-LCD application, the duty cycle is very low. Even with high values of voltage and current, the power dissipation is low and the chip does not shut down.

Applications Information

Output Load

The MAX9650/MAX9651 are designed to drive capacitive loads. A small value of series resistance improves the performance of the device to ensure stability and fast settling with very large or very small capacitive loads. In many cases, this resistance is already present due to connection resistance in the wiring and no additional physical resistor is necessary.

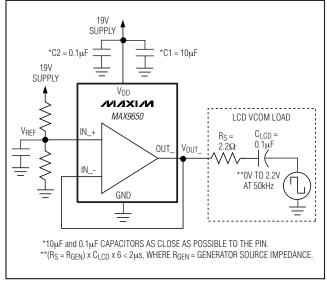


Figure 1. Settling Time Test Circuit

Power Supplies and Bypass Capacitors

The MAX9650/MAX9651 operate from a 6V to 20V single supply or from $\pm 4.5 V$ to $\pm 10 V$ dual supplies. Proper supply bypassing ensures stability while driving high transient loads. The MAX9650/MAX9651 require a minimum $10 \mu F$ (C1) and $0.1 \mu F$ (C2) power-supply bypass capacitors placed as close as possible to the power-supply pin

 $(V_{DD}).$ See Figure 2. For dual-supply operation, use 10µF and 0.1µF bypass capacitors on both supplies (V_DD and GND) with each capacitor placed as close as possible to V_DD and GND.

Layout and Grounding

The exposed pad on the μ MAX® and TDFN packages provide a low thermal resistance for heat dissipation. Solder the exposed pad to a ground plane for best thermal performance. Do not route traces under these packages. For dual-supply operation, the exposed pad (EP) can be electrically connected to the negative supply or it can be left unconnected.

Chip Information

PROCESS: BICMOS

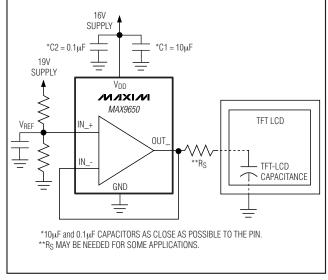
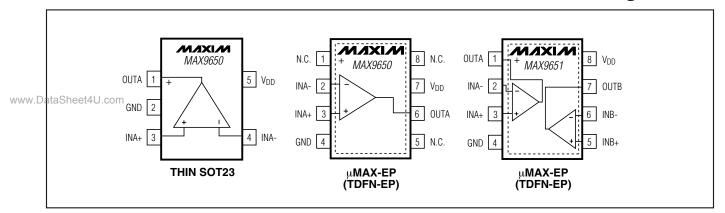


Figure 2. Typical TFT-LCD Backplane Drive Circuit

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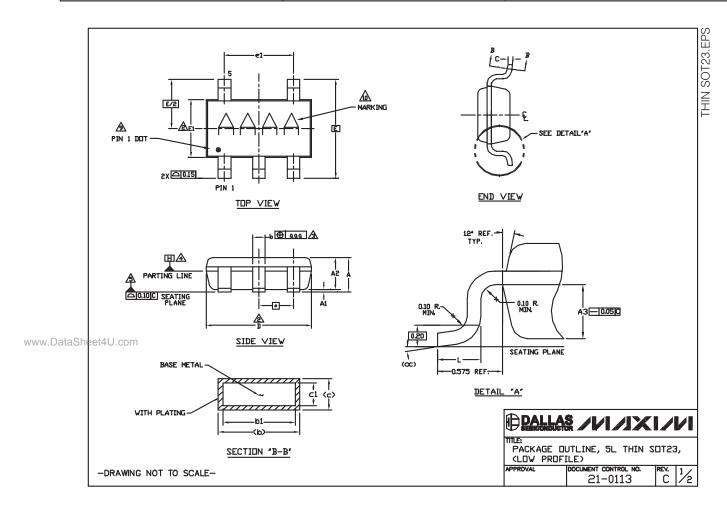
Pin Configurations



Package Information

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages

| PACKAGE TYPE | PACKAGE CODE | DOCUMENT NO. |
|--------------|--------------|----------------|
| 5 SOT23 | Z5-2 | <u>21-0113</u> |
| 8 μMAX | U8E-2 | 21-0107 |
| 8 TDFN-EP | T833-2 | <u>21-0137</u> |



Package Information (continued)

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

NUTES

1. ALL DIMENSIONS ARE IN MILLIMETERS.

'D' AND "E1" ARE REFERENCE DATUM AND DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, AND ARE MEASURED AT THE BOTTOM PARTING LINE. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15mm ON "D" AND 0.25mm ON "E" PER SIDE.

THE LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.07mm TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION.

DATUM PLANE "H" LUCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT THE BOTTOM OF PARTING LINE.

THE LEAD TIPS MUST LINE WITHIN A SPECIFIED TOLERANCE ZONE. THIS TOLERANCE ZONE IS DEFINED BY TWO PARALLEL LINES. DNE PLANE IS THE SEATING PLANE, DATUM L-C-J, AND THE OTHER PLANE IS AT THE SPECIFIED DISTANCE FROM L-C-J IN THE DIRECTION INDICATED. FORMED LEADS SHALL BE PLANAR WITH RESPECT TO DNE ANOTHER WITH 0.10mm AT SEATING PLANE.

THIS PART IS COMPLIANT WITH JEDEC SPECIFICATION MD-193 EXCEPT FOR THE "e" DIMENSION WHICH IS 0.95mm INSTEAD OF 1.00mm. THIS PART IS IN FULL COMPLIANCE TO EIAJ SPECIFICATION SC-74.

COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS. COPLANARITY SHALL NOT EXCEED 0.08mm.

8. WARPAGE SHALL NOT EXCEED 0.10mm.

9. THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 PP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.

10 MARKING IS FOR PACKAGE DRIENTATION REFERENCE ONLY.

11. ALL DIMENSIONS APPLY TO BOTH LEADED (-> AND LEAD FREE (+) PACKAGE CODES.

| SYMBOLS | | | | | | | |
|------------|-----------|-------------|------|--|--|--|--|
| | MIN | MIN NOM MAX | | | | | |
| Α | ı | - | 1.10 | | | | |
| A1 | 0.00 | 0.075 | 0.10 | | | | |
| A2 | 0.85 | 0.88 | 0.90 | | | | |
| A3 | | 0.50 BSC | | | | | |
| b | 0.30 | - | 0.45 | | | | |
| b1 | 0.25 | 0.35 | 0.40 | | | | |
| c | 0.15 | - | 0.20 | | | | |
| c 1 | 0.12 | 0.127 | 0.15 | | | | |
| D | 2.80 | 2.90 | 3.00 | | | | |
| E | 2.75 BSC | | | | | | |
| E1 | 1.55 | 1.60 | 1.65 | | | | |
| L | 0.30 | 0.40 | 0.50 | | | | |
| €1 | 1.90 BSC | | | | | | |
| е | 0.95 BSC | | | | | | |
| oc | 0* | 4* | 8* | | | | |
| aaa | 0.20 | | | | | | |
| Pkg. c | odesi Z5- | 1, Z5-2 | | | | | |

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PALLAS /VI/IXI/VI

PACKAGE DUTLINE, 5L THIN SDT23,

(LOW PROFILE) DOCUMENT CONTROL NO.

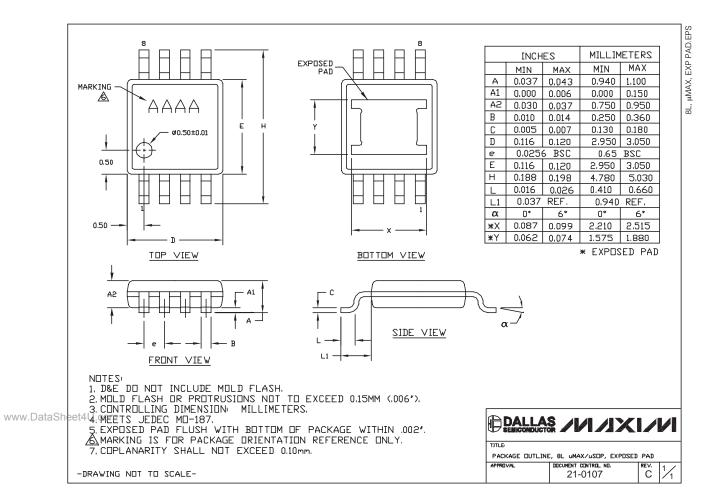
21-0113

С

-DRAWING NOT TO SCALE-

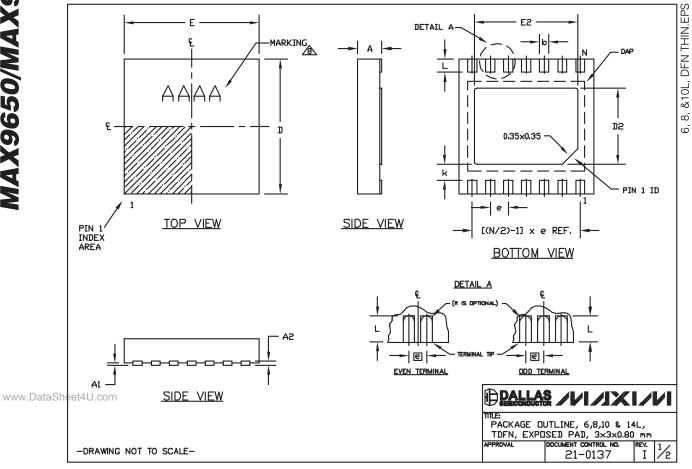
Package Information (continued)

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.



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For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.



Package Information (continued)

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

| COMMON DIMENSIONS | | | | | | |
|-------------------|-----------|------|--|--|--|--|
| SYMBOL | MIN. | MAX. | | | | |
| Α | 0.70 | 0.80 | | | | |
| D | 2.90 | 3.10 | | | | |
| E | 2.90 | 3.10 | | | | |
| A1 | 0.00 | 0.05 | | | | |
| L | 0.20 | 0.40 | | | | |
| k | 0.25 MIN. | | | | | |
| A2 | 0.20 REF. | | | | | |

| PACKAGE VARIATIONS | | | | | | | |
|--------------------|----|-----------|-----------|----------|----------------|-----------|---------------|
| PKG. CODE | N | D2 | E2 | е | JEDEC SPEC | b | [(N/2)-1] x e |
| T633-2 | 6 | 1.50±0.10 | 2.30±0.10 | 0.95 BSC | MO229 / WEEA | 0.40±0.05 | 1.90 REF |
| T833-2 | 8 | 1.50±0.10 | 2.30±0.10 | 0.65 BSC | MO229 / WEEC | 0.30±0.05 | 1.95 REF |
| T833-3 | 8 | 1.50±0.10 | 2.30±0.10 | 0.65 BSC | MO229 / WEEC | 0.30±0.05 | 1.95 REF |
| T1033-1 | 10 | 1.50±0.10 | 2.30±0.10 | 0.50 BSC | MO229 / WEED-3 | 0.25±0.05 | 2.00 REF |
| T1033-2 | 10 | 1.50±0.10 | 2.30±0.10 | 0.50 BSC | MO229 / WEED-3 | 0.25±0.05 | 2.00 REF |
| T1433-1 | 14 | 1.70±0.10 | 2.30±0.10 | 0.40 BSC | | 0.20±0.05 | 2.40 REF |
| T1433-2 | 14 | 1.70±0.10 | 2.30±0.10 | 0.40 BSC | | 0.20±0.05 | 2.40 REF |

-DRAWING NOT TO SCALE-

- 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
- 2. COPLANARITY SHALL NOT EXCEED 0.08 mm.
- 3. WARPAGE SHALL NOT EXCEED 0.10 mm.
- 4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
- 5. DRAWING CONFORMS TO JEDEC MO229, EXCEPT DIMENSIONS "D2" AND "E2", AND T1433-1 & T1433-2.

- 6. "N" IS THE TOTAL NUMBER OF LEADS.
 7. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.

 AMARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.

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PALLAS /VI/IXI/VI

21-0137

PACKAGE DUTLINE, 6,8,10 & 14L, TDFN, EXPOSED PAD, 3×3×0.80 mm

PPROVAL | DOCUMENT CONTROL NO. | IREV.

Ι

Revision History

| REVISION NUMBER | REVISION DATE | DESCRIPTION | PAGES CHANGED |
|--------------------|------------------|---|------------------|
| 0 | 7/08 | Initial release | _ |
| 1 | 10/08 | Updated slew rate and added TDFN-EP package | 1, 2, 6, 10, 11 |
| 2 | 5/09 | Updated continuous output current specification | 2 |

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